

### **REMARKS**

Claims 46-64 remain pending in this application. Each of the pending claims is believed to define an invention that is novel and unobvious over the cited references. Favorable reconsideration of this case is respectfully requested.

The drawings have been objected to as not showing every feature specified in the claims. Submitted herewith on a separate sheet is a replacement drawings for Figure 18B. Figure 18B incorrectly reverses the base resin 2 and the isolating film 4. Please compare corrected Figure 18B with Figure 18B in the parent application Serial Number 08/944,891 filed October 6, 1997 now U.S. Patent Number 6,246,114. Please note that the embodiments shown in Figures 18A-18C of the present application are a variation of the embodiment shown in Figures 2A-2B. Figure 18B is now corrected to correspond to the originally filed Figure 18B in the above-noted parent application.

Consequently, it can now been seen in the Figures that the elements 182A shown in Figure 18C illustrate the plurality of electrodes on main surface of the semiconductor chip 182. Further, the base resin 2 is formed on the main surface of the semiconductor chip 182 as seen in the corrected Figure 18B.

In view of the above, it is respectfully submitted that the Figures show every feature of the invention specified in the claims. Therefore, the withdrawal of the objection to the figures is respectfully requested.

Claims 46-57 have been rejected under 35 U.S.C. 112, second paragraph as being indefinite. Claims 46 and 52 have been amended to recite that the conductive patterns extend in the through holes. Consequently, it is respectfully submitted that all pending claims are now in all aspect in compliance with 35 U.S.C. 112. Therefore, the withdrawal of this rejection is respectfully requested.

Claims 46-49 and 52-55 are rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Patent Number 5,841,192 to Exposito. Exposito does not anticipate the claimed invention as it does not disclose, among other things, electrodes formed on the main surface of the chip.

The rejected claims, for example, reading independent claim 46 on Figures 18A-18B, recite a semiconductor chip 182 having a main surface and a back surface. A plurality of a electrodes 182A are arranged on the main surface of the semiconductor chip 182. A base resin film 2 is formed on the main surface of the semiconductor chip. The base resin film 2 has a first surface 181B facing the main surface of the semiconductor chip 182 and a second surface 181A opposite to the first surface. A plurality of conductive pattern 3 are formed on the first surface 181B of the base resin film. An insulating film 4 is formed on the first surface 181B of the base resin film 2.

In comparison, Exposito does not disclose a plurality of electrodes arranged on the main surface of the semiconductor chip. Exposito describes a resin 1 which extends from an upper surface of an insulating plate 2 carrying an integrated circuit chip 3 up to at least the periphery of the lower surface of the plate 2, please see Figure 1 and column 2, lines 49-54 of Exposito. As can be seen in Figure 1 of Exposito, the resin 1 covers the entire structure. Balls 5, which are alleged to correspond to the plurality of electrodes, are formed on the plate 2, not on the main surface of the semiconductor chip as is recited in the present claims. As can be seen in Figure 1, the resin film 1 having electrode holes formed therein, are formed at the rear surface of the chip 3.

Accordingly, it is clear that the cited reference does not disclose each and every element recited in the rejected claims, for example a semiconductor chip having a main surface and a plurality of electrodes arranged on a main surface of a semiconductor chip, as is recited in the rejected claims as shown in, for example Figure 18C. Therefore, the withdrawal of this rejection is respectfully requested.

If the Examiner is of the opinion that the prosecution of this application would be advanced by a personal interview, the Examiner is invited to telephone undersigned counsel to arranged for such an interview.

Application No. 10/762,347  
Amendment dated  
Reply to Office Action of April 10, 2007

Docket No.: 32305-200192


The Commissioner is authorized to charge any fee necessitated by this Amendment to our Deposit Account No. 22-0261.

In view of the above amendment, applicant believes the pending application is in condition for allowance.

Dated: 7/31/07

Respectfully submitted,

By

*for*  47709  
James R. Burdett

Registration No.: 31,594

VENABLE LLP

P.O. Box 34385

Washington, DC 20043-9998

(202) 344-4000

(202) 344-8300 (Fax)

Attorney/Agent For Applicant